

Polystyrene hard foam moulded articles.**Publication number:** EP0620246 (A1)**Publication date:** 1994-10-19**Inventor(s):****Applicant(s):** ALGOSTAT GMBH & CO KG [DE]**Classification:****- international:** C08J9/00; C08K3/04; C08J9/00; C08K3/00; (IPC1-7): C08L25/06; C08J9/00; C08J9/224**- European:** C08J9/00M; C08K3/04**Application number:** EP19940105521 19940409**Priority number(s):** DE19930005431U 19930413**Also published as:** EP0620246 (B1)
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 AT176261 (T)**Cited documents:** GB916776 (A)
 FR2230667 (A1)
 DE1173244 (B)
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Abstract of EP 0620246 (A1)

Mouldings produced from rigid polystyrene foam or polystyrene particle foam are used for insulation purposes. It has been found that rigid polystyrene foam having a density of less than 20 kg/m³ has a higher thermal conductivity than rigid polystyrene foam having a higher density. The invention has the object of providing a moulding made from rigid polystyrene foam which has a density of less than 20 kg/m³ and a favourable thermal conductivity. This object is achieved according to the invention by providing the rigid polystyrene foam with an athermanous material. The consequence of this is that corresponding mouldings having a density of less than 20 kg/m³ have a thermal conductivity which is no greater or not significantly greater than the thermal conductivity of rigid polystyrene foam having a density of about 40 kg/m³ with relatively low thermal conductivity. The invention is particularly suitable for sheet-like mouldings made from polystyrene particle foam for insulation in the construction (building) sector.

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